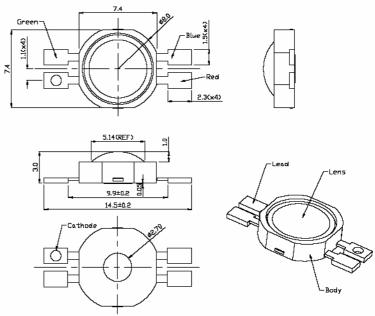


Features

- Highest Lumen Per Watt
- Long Operational Life
- White Housing
- Superior ESD Protection
- 1W per color; Total 3W per package
- Instant Light (less than 100ns)
- Compatible to Luxeon's "Lambertian"
- True SMD Emitter
- IR Reflow Soldering Process
- Lead (Pb) Free RoHS compliant

Package Dimension



Tolerance:

Note: Lens is low dome profile

± see spec

Unit: mm

Applications

- Full Color Down Light/Spot Light
- Automotive Exterior/Interior Light
- Marine/Miner's Lighting
- Portable Flashlight/ General Lighting

Optical Characteristics at T₁=25°C, I_F=350mA each color

PART NUMBER	IMBER Emitting LED Chip Color Material		Lens Color	Wavelength (nm) CCT (K) Range		Drive Voltage @ 350mA	Luminous Flux (lm) @350mA	VIEW ANGLE 201/2
			COIOI	Min	Max	Тур.	Тур.	(deg)
BTP3-99RGBCG-XX-X/W	Normal Red	AllnGaP	Water Clear	615	645	2.20V	30 lm	
	Green	AllnGaN		520	550	3.55V	30 lm	140
	Blue			460	485	3.55V	10 lm	

Notes:

- 1) Picture for illustration purpose only. Please refer to outline dimension for actual package size.
- 2) Flux is measured with the accuracy of ±15%. Please refer to Flux Selection Guide
- 3) CCT is measured with the accuracy of \pm 400K. Please refer to CCT Selection Guide
- 4) V_F is measured with the accuracy of \pm 0.15V. Please refer to V_F Selection Guide

Part No.: BTP3-99RGBCG-XX-X/W Rev1.2005 Page 1 of 10



Absolute Maximum Ratings at T_J=25°C

Parameter	Red	Blue/Green	
Power Dissipation (W)	1.00	1.22	
DC Forward Current (mA) ^[1]	350	350	
Peak Pulsed Forward Current (mA) [4]	500	500	
Average Forward Current (mA)	350		
Reverse Voltage (V)	5		
Reverse Current (uA)	50		
ESD Sensitivity (V) [2]	16,000		
LED Junction Temperature at 350mA (°C) [3]	120	135	
Storage Temperature (°C)	-40 to +105		
Operating Temperature (°C)	-40 to +105		
Lead Soldering Temperature (°C) ^[4]	260°C for 5 seconds max		

Application Notes:

- Proper forward current must be observed to maintain the junction temperature below maximum rating
- 2. Although all products listed are class one ESD protection (+/- 16KV by HBM mode), care must be fully taken when handling products
- 3. Specification is subjected to change for improvements without notice.
- 4. Test conditions: tp≤10us, duty cycle = 0.005
- 5. CAUTION: When lighting up, the emitter will become very hot if it is not attached to a heat sink. Please provide proper heat management to prevent damage to the emitter.

WARNING
This range of LEDs is produced with die having a high radiant flux.
Care must be taken when viewing the product at close range as the light may be intense enough to cause damage to the human eye.

Note: Industry standard procedures regarding static must be observed when handling this product.

Part No.: BTP3-99RGBCG-XX-X/W Rev1.2005 Page 2 of 10



CCT, Flux and V_F Selection Guide (@T_J=25°C, I_F=350mA)



Travolongin Ranko Coloction				
Color	Bin	λ _D (nm)		
COIOI	Dill	Min	Max	
Blue	B5	460	465	
	B6	465	470	
	B7	470	475	
	B8	475	480	
	XX	460 – 475		
	G7	520	525	
	G8	525	530	
Green	G9	530	535	
	G10	535	540	
	XX	520 – 540		
Red	XX	615	645	

Color	Bin	Flux (lumens)	
	K	8~10	
Blue	L	10~14	
Diue	M	14~18	
	X	Default Full Range	
	X P	23~30	
Red	Q	30~39	
Green	R	39~50	
	X	Default Full Range	

Part No.: BTP3-99RGBCG-XX-X/W Rev1.2005 Page 3 of 10



Typical Electro-Optical Characteristics Curves

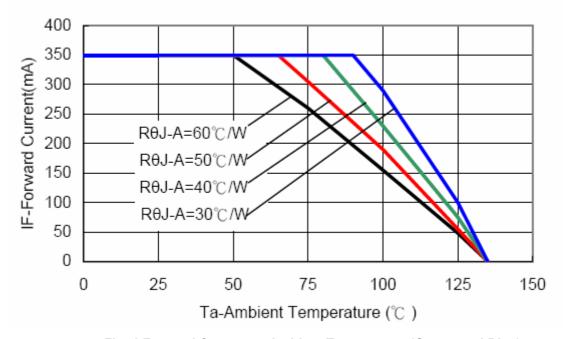


Fig. 1 Forward Current vs Ambient Temperature (Green, and Blue)

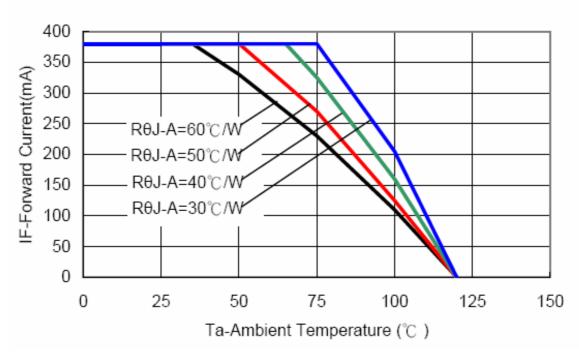


Fig. 2 Forward Current vs Ambient Temperature (Red)

Part No.: BTP3-99RGBCG-XX-X/W Rev1.2005 Page 4 of 10



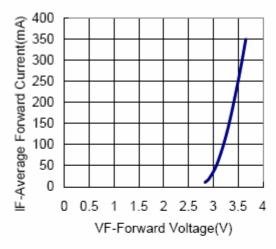


Fig 3a. Forward Current vs. Forward Voltage for Blue and Green.

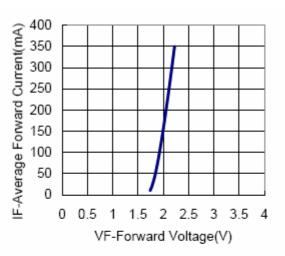


Fig 3b. Forward Current vs. Forward Voltage for Red.

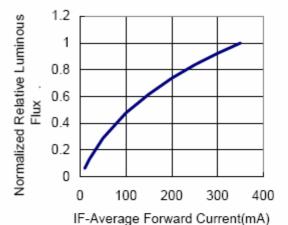


Fig 4a. Relative Luminous Flux vs. Forward Current for Blue and Green at Tj=25°C maintained.

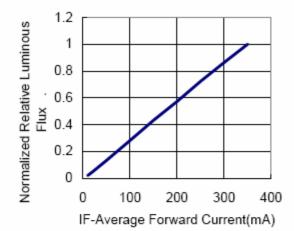


Fig 4b. Relative Luminous Flux vs. Forward Current for Red at Tj=25°C maintained.

Part No.: BTP3-99RGBCG-XX-X/W Rev1.2005 Page 5 of 10



Typical Electro-Optical Characteristics Curves

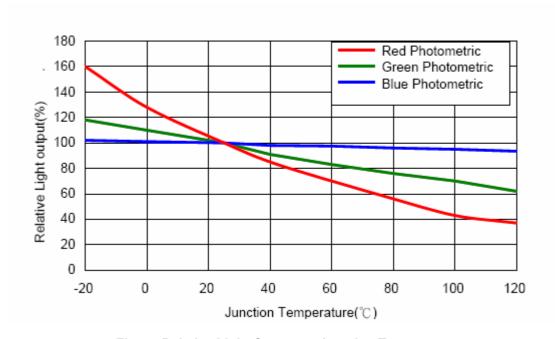


Fig. 5a Relative Light Output vs Junction Temperature

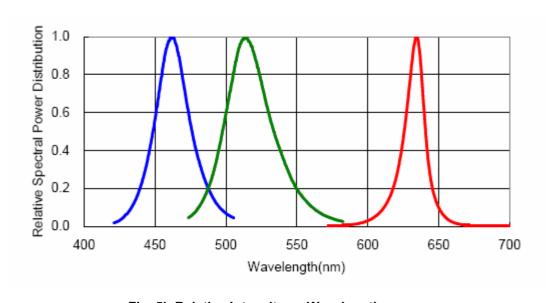


Fig. 5b Relative Intensity vs Wavelength

Part No.: BTP3-99RGBCG-XX-X/W Rev1.2005 Page 6 of 10



Typical Electro-Optical Characteristics Curves

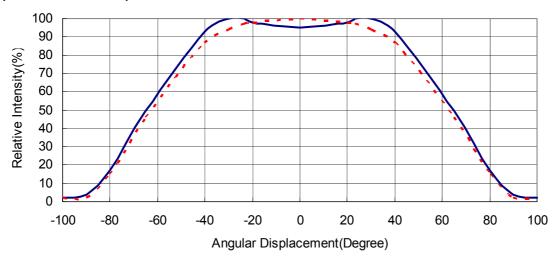


Fig. 6 Typical Radiation Pattern

Recommended Solder Pads Layout

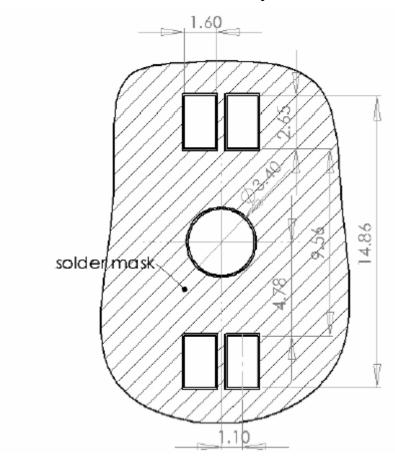
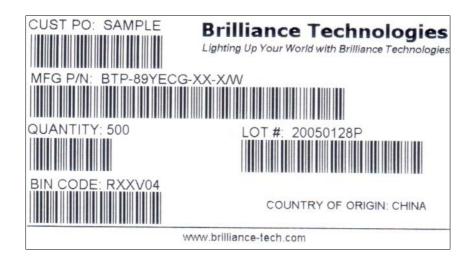


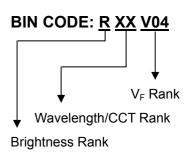
Fig. 7 Recommended Solder Pads Dimension

Part No.: BTP3-99RGBCG-XX-X/W Rev1.2005 Page 7 of 10

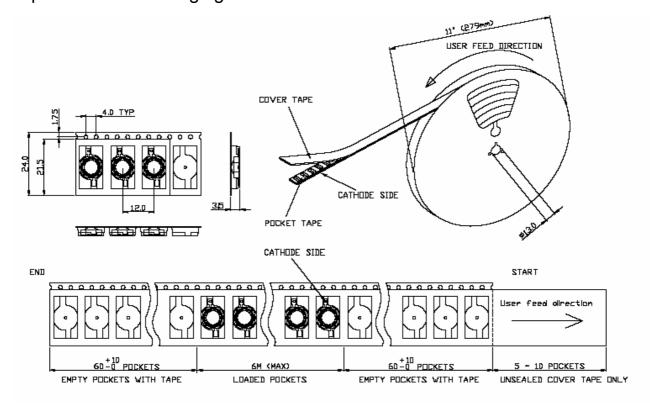


Product Barcode Label





Tape and Reel Packaging Dimension



Note: The emitter should be picked up by the body (not lens) during placement. The inner diameter of the pick-up collect should be greater or equal to 6.5mm

Part No.: BTP3-99RGBCG-XX-X/W Rev1.2005 Page 8 of 10



Recommended IR Reflow Conditions

Reflow Soldering				
	Lead Solder	Lead-Free Solder		
Pre-heat	120~150°C	180~200°C		
Pre-heat time	120 sec Max	120 sec Max		
Peak Temperature	240°C Max	260°C Max		
Soldering Time	10 sec Max	10 sec Max		
Conditions	Refer to Temperature profile A	Refer to Temperature profile B (N ₂ reflow is recommended)		

Temperature Profile A (Surface of MCPCB)

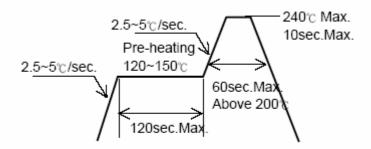


Figure 8a. Lead Solder Temperature Profile

Temperature Profile B (Surface of MCPCB)

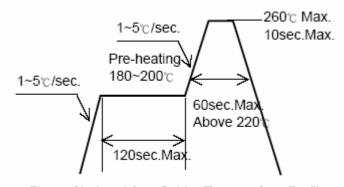


Figure 8b. Lead-free Solder Temperature Profile

Part No.: BTP3-99RGBCG-XX-X/W Rev1.2005 Page 9 of 10



IR Reflow Process Notes

- Occasionally there is a brightness decrease due to the influence of heat or ambient during air reflow. It is recommended that customer use nitrogen reflow method.
- Repairing should not be done after the LEDs have been soldered. When repairing is required, double-head soldering iron should be used. Customer should confirm whether the characteristics of the LEDs will or will not damaged before carrying out the repair.
- Reflow soldering should not be done more than two times
- When soldering, do not put stress on the LEDs during heating.
- After soldering, do not warp the circuit board.

Manual Hand Soldering Notes

- For prototype builds or small production runs, it is possible to place and solder the emitters.
- It is recommended to hand solder the leads and slug with a solder tip temperature of 230°C for less than 10seconds. This profile ensures a junction temperature below the maximum of 120°C, avoiding damage to the emitter or to the MCPCB dielectric layer. Damage dielectric layer can cause a short circuit in the array.

Other Important Notes:

- The information contained herein is presented only as a Guide for the application of our products. Brilliance Technologies assumes no responsibility for any infringement of intellectual property or other rights of the third parties which may result from its use.
- Brilliance Technologies continually improves the quality of our products. Nevertheless, semiconductor devices in general can malfunction or fail due to their inherent electrical sensitivity and vulnerability to physical stress. It is the responsible of the customer, when using Brilliance Technologies products, to comply with the standard of safety in making a safe design for the entire system, and to avoid situations in which a malfunction or failure of such Brilliance Technologies products cause loss of human life, bodily injury or damage to property.
- Brilliance Technologies products listed in this data sheet are intended for usage in general
 electronics and/or non-commercial or industrial lighting products. These products are neither
 intended nor warranted for usage in equipment that requires extraordinarily high quality and/or
 reliability or a malfunction or failure of which may cause loss of human life or bodily injury.
- In developing your design, please ensure that Brilliance Technologies products are used within specified operating ranges as set forth in the most recent Brilliance Technologies data sheets.

BT-Rev. 1.0A20050119

Specifications are subject to change for improvement without notice. Copyright © 2003 Brilliance Technologies Co., Ltd. All rights reserved.

Part No.: BTP3-99RGBCG-XX-X/W Rev1.2005 Page 10 of 10